

DIE COMPACTED TIPS

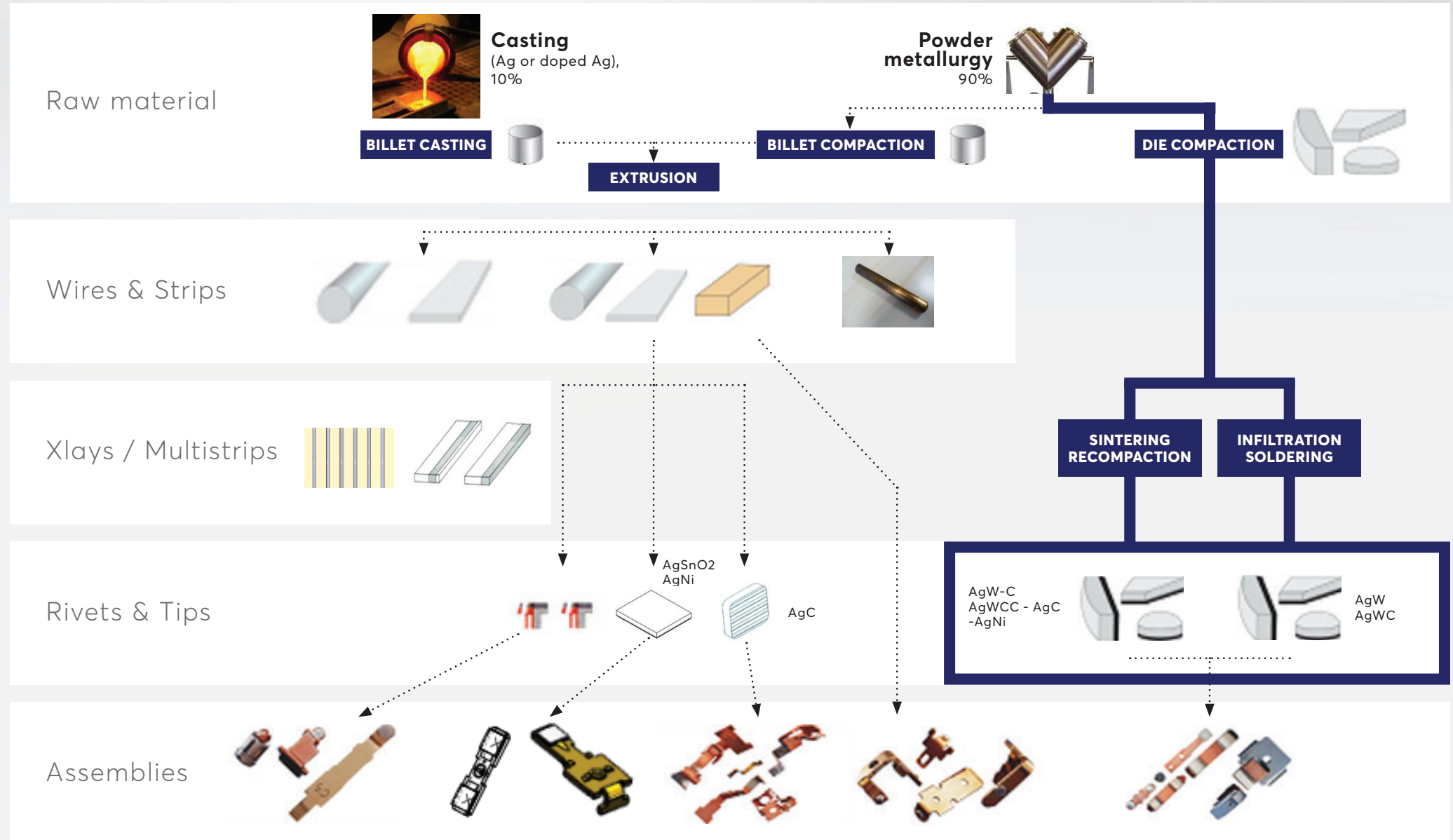
PROCESS DESCRIPTION



PRODUCTION FLOW CHART

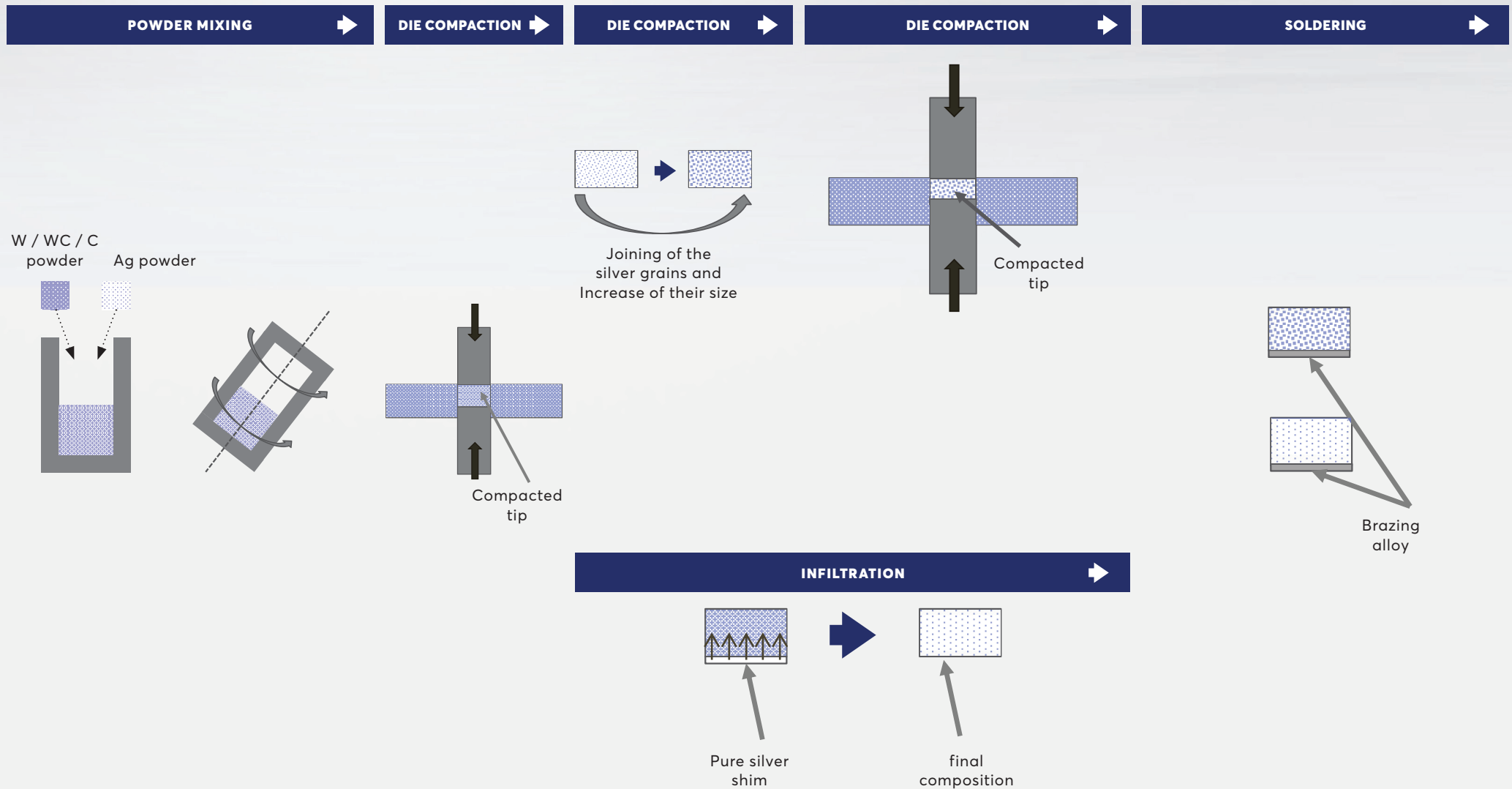
METALOR TECHNOLOGIES ELECTROTECHNICS FRANCE

METALOR®  A member of TANAKA



DIE COMPACTED TIPS:

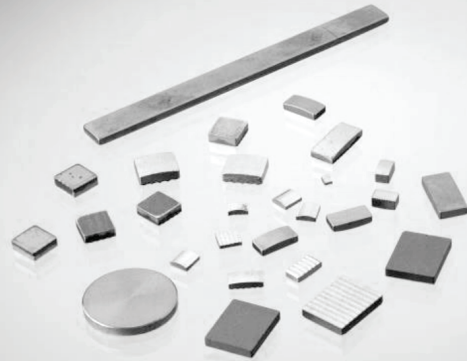
PROCESS FLOW



DIE COMPACTED TIPS: APPLICATIONS

PRODUCTS

DIE COMPACTED TIPS



APPLICATIONS

PROTECTION Circuit Breakers



KEY END MARKETS

INDUSTRIAL BUILDING



MCB

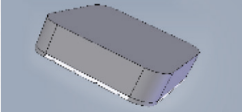
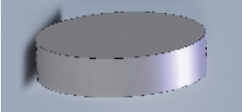
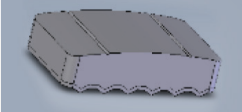

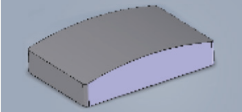
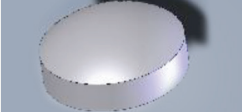


HOME CONTROL



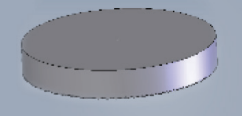
DIE COMPACTED TIPS:

TYPE OF PRODUCT

TECHNOLOGY	MATERIAL	COMPOSITION(%)	SHAPE		DIMENSIONS (mm)	SILVER UNDERLAYER (BI-COMPACTION)	SOLDERING
SINTERED/ CALIBRATED	AgC	Graphite: 3 and 5%	Square/ rectangle		Min: 3.2 x 3.2 Max: 25.0 x 12.5	✗	✗
			round		Min: Ø3.0 Max: Ø5.0	✗	✗
	AgW	Tungsten: 50%	Square/ rectangle		8.7 x 5.0	✓	✓
			round	✗	✗	✗	✗
	AgWC	WC 20 and 80%	Square/ rectangle		Min: 7.0 x 4.0 Max: 15.0 x 12.0	✓	✓
			round	✗	✗	✗	✗
	AgNi	Ni 10 to 30%	Square/ rectangle		Min: 10.0 x 6.5 Max: 24.0 x 18.5	✗	✓
			round		Ø3.2	✗	✓

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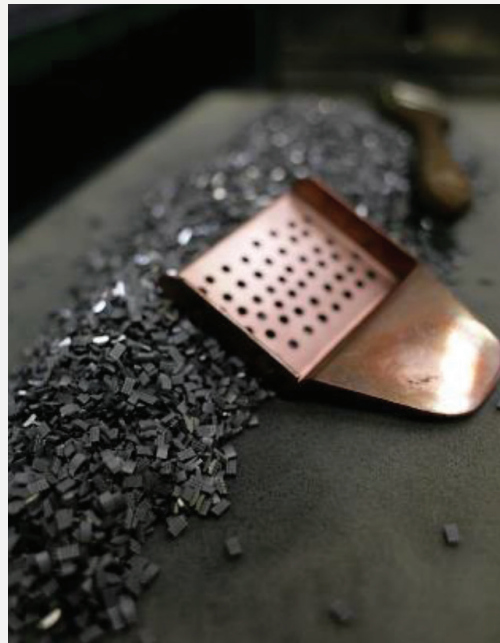
TYPE OF PRODUCT

TECHNOLOGY	MATERIAL	COMPOSITION(%)	SHAPE		DIMENSIONS (mm)	SOLDERING
INFILTRATED	Agw	Tungsten: 40 to 75%	Square/ rectangle		Min: 5.0 x 1.0 Max: 37.5 x 20	✓
			Round		Ø6	✓
	AgWC	WC: 30 to 80%	Square/ rectangle		Min: 3.0 x 2.0 Max: 22.0 x 20.0	✓
			Round		Min: Ø3.7 Maxi: Ø22.0	✓

All of these information are based on our current production.
For further information or outer dimension, please contact METALOR

DIE COMPACTED TIPS: PROCESS PICTURES

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DIE COMPACTED TIPS: PERFORMANCE VS TECHNOLOGY

PROS	CONS
<ul style="list-style-type: none">- Standard process by METALOR- Competitiveness for high volumes- Different type of technologies	<ul style="list-style-type: none">- not for all material composition

For more information,
please contact **METALOR**
team on our Web site:
www.metalor.com

